



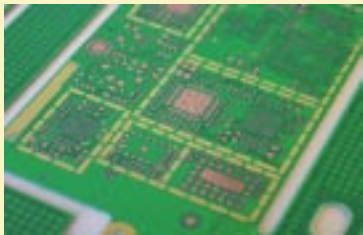
European Institute of Printed Circuits

# EIPC Summer Conference 2005 and Table Top Exhibition on PCB technologies, cost and innovation



World Electronic Circuits Council

The EIPC is the European representative at the World Electronics Circuit Council



**June 9 and 10, 2005**  
**Stockholm, Sweden**  
*Location: Scandic Infra City Hotel*

## Programme:

### Topics to be included

- Lead free technology
- Advanced laminate and prepreg
- InkJet technology in PCB fabrication
- Environmental issues
- New PCB technology and cost
- Micro via hole layer technology
- Rigid flex PCB technology introduced in rigid PCB fabrication processes
- Environmental testing and UL-Approvals for new type of PCBs
- Management items
- Networking at all levels
- Table Top Exhibition
- Cultural events

Sponsors:



MacDermid



For more details contact the EIPC:  
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**EIPC Summer Conference Stockholm  
June 9 & 10, 2005**

**Electronics made in Europe  
The challenge for the PCB fabricators**

*"Exchange and network with the PCB professionals in technology"*

**PROGRAMME**

The European Institute of Printed Circuits (EIPC) is extending an invitation to companies and individuals active in the Packaging and Interconnection Industry to participate in the EIPC Summer Conference to be held on June 9 & 10, 2005 in Stockholm, Sweden.

The aim of the Summer Conference is to provide a platform for speakers and delegates to exchange information on market conditions and future innovation on interconnection and packaging. Delegates and visitors from throughout Europe will attend this event, offering presenters the opportunity to reach a targeted audience of decision makers and leaders of the international packaging and interconnection industry.

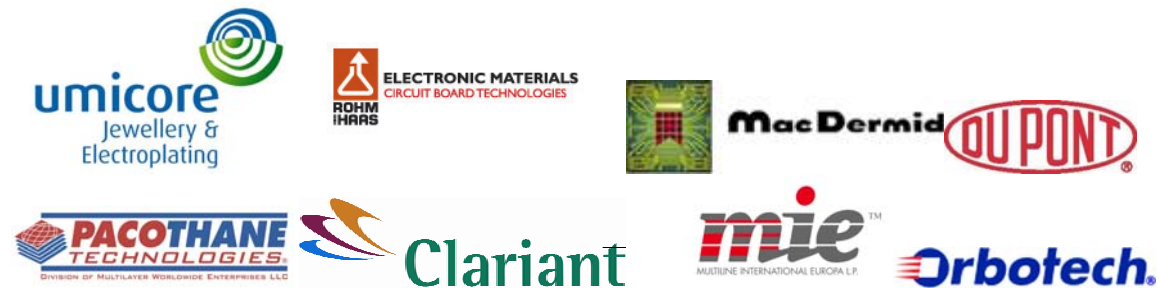
This conference is an absolute 'must' for companies associated with PCB fabrication who wish to stay up to date with the latest market requirements, materials, fabrication equipment and manufacturing processes who also need to improve the efficiency of their processes and the reliability of their products.

**WHO SHOULD ATTEND?**

Engineers and decision-makers in the field of OEMs, EMS, assembly, and PCB fabricators as well as board and system designers at all levels are invited to participate. Circuit board designers, looking into more cost-effective solutions and miniaturisation, will learn about the developing trends in different applications. Board fabricators and development engineers will gain background information that will help to focus on more profitable products. Specialists and marketing managers will gain additional background data to focus on advanced PCB applications. OEMs will get a better understanding on how to get prepared for the next generation of electronic products.

**WHY STOCKHOLM?**

Stockholm is the capital city of Sweden, and is beautifully situated on a group of islands between Lake Malara and the Baltic Sea. Indeed, so numerous are the bridges linking these islands that Stockholm has been called the 'Venice of the North'. The city was founded in 1255, taken over by the Danes in 1389 and again in 1520. It has a population of less than 2 million. The old town, Staden, has picturesque gabled houses and narrow streets and provides a taste of the city before much of the old buildings were destroyed by fire. The Staden is the location of the Royal Palace, and St. Nicholas Church (13<sup>th</sup> Century) and the House of the Nobles (17<sup>th</sup> Century) all which are worthy of a visit after the conference. Food in Sweden is taken seriously, and is always delicious. The nightlife is excellent, but be careful, it never really gets dark in June, so you may not get to bed at all!



the official sponsors of the EIPC Summer Conference Stockholm 2005



**EIPC Summer Conference Stockholm June 9 & 10, 2005**

**Wednesday June 8: 18:00-20:00 Conference Registration and Table Top & Poster build up**

**Programme Day 1, Thursday June 9**

<b>07:30</b>	<b>Conference Registration and Table Top &amp; Poster build up</b>	<b>Scandic Infra City Hotel</b>
<b>08:15</b>	<b>Welcome by the President</b>	<b>Paul Waldner, EIPC</b>
	<b>Session 1: Advanced Management/Technology</b>	<b>Moderator: Russ Crockett, DuPont</b>
08:30	Dynamics and future trends	Walt Custer, Custer Consulting, US
09:00	Dry film photo resist technology for profitable western PCB production	Mats Ehlin, DuPont Printed Circuit Materials, US
09:30	Environmental testing and UL-Approvals for new type of PCBs	Stephen Street, UL International (UK) Ltd.
10:00	Advances in Inkjet Materials for Interconnect Applications	Tom Sutter, Rohm and Haas Electronic Materials, US
<b>10:30</b>	<b>30 minutes Coffee Break</b>	Table Top & Poster Display area
	<b>Session 2: Surface Finishes for Lead Free Soldering</b>	<b>Moderator: Giovanni Tridenti, Somacis</b>
11:00	High temperature OSP and SIT in lead free soldering	Harri Latonen, Tarja Rapala-Virtanen, Aspocomp, Finland
11:30	Solder Joint Reliability of Tin-Zinc-Bismuth Lead-free solder under environmental stress	Katsumasa Suyama, Espec Corp., Japan
12:00	A case study on the influence of Lead free process on the optical inspection capabilities of AOI systems	Harald Eppinger, Orbotech-Schuh GmbH & Co. KG, Germany
12:30	Lead Free Flip Chip and Chip Scale Package Inspection: New Challenges Will Require New Inspection Technologies	Mark Cannon, ERSA GmbH, Germany
<b>13:00</b>	<b>Lunch</b>	Scandic Infra City Hotel Restaurant
	<b>Session 3: Embedded Components</b>	<b>Moderator: Steve Jones, Circatex Ltd.</b>
14:30	Embedded passives and data Infrastructure	Tero Kärkkäinen, Nokia Technology Platforms, Finland
15:00	The impacts of embedded active & passive components	Martin Cotton, Sanmina SCI, UK
15:30	Embedded passive in BGA interposer structures for avionic applications	Marcus Bärtele, Defence Electronis EADS Germany
<b>16:00</b>	<b>30 minutes Coffee Break</b>	Table Top & Poster Display area
	<b>Session 4: PCB surfaces for Lead free</b>	<b>Moderator: Martin Goosey, Rohm and Haas Electronic Materials</b>
16:30	Solderability of PCB Surfaces with Lead Free Solders Application of Test Methods and Comparative Results for Immersion tin, Immersion Silver and Electroless Nickel / Immersion Gold	Peter Meeh, MacDermid GmbH, Germany
17:00	Vertical Continuous Transfer type Electrolytic Copper Plating Machinery for new PCB technology	Mr. H. Otake, Umicore Galvanotechnik GmbH, Germany
17:30	The effects of lead free surface finish on solderjoint microvoids	Don Cullen, MacDermid, Inc. UK
18:00	New-highest reliable generation of Pwb surface finishes for lead free soldering applications	Frando van der Pas, Cookson Electronis, Enthone, UK
<b>18:30</b>	<b>End of the first day</b>	
<b>19:00</b>	<b>Departure by bus for Networking Dinner and Evening Tour Stockholm</b>	Hotel Lobby



**EIPC Summer Conference Stockholm June 9 & 10, 2005**

**Programme Day 2, Friday June 10**

	<b>Session 5: Flexible Circuits &amp; Microvia layers</b>	<b>Moderator: Alan Hanson, MacDermid</b>
08:30	Evolution of a wiring concept- 30 years of flex rigid circuit board production	Markus Wille, Ruwel AG, Germany
09:00	Critical analysis of common make-up materials for flex cover layers, comparing the relative amount of adhesive squeeze-out into standard apertures	Daniel Kush, Pacothane, US
09:30	Laser cutting of flex and rigid PCB materials using CO2 and UV lasers	Marc Hüske, LPKF Laser and Electronics AG, Germany
10:00	Accuracy and reference for laser via holes in SBU	Giacomo Angeloni, Somacis pcb Industries
<b>10:30</b>	<b>30 minutes Coffee Break</b>	Table Top & Poster Display area
11:00	Semi-flexible base material -Characteristics and applications	Wolfgang Alberth, Isola GmbH, Germany
11:30	Halogen free laminates: worldwide trends, driving forces and state of play	Jérôme De Boysère, Clariant GmbH, Germany
12:00	Lead Free Assembly: A Practical Tool for Laminate Materials Selection	David Humby, Polyclad Laminates, UK
12:30	The Impact of PCB Material Dielectric Properties on High-Speed Digital System: From a system designer's perspective	Young Y. Gao, Rogers Corporation, US
<b>13:00</b>	<b>Networking Lunch</b>	
<b>14:30</b>	<b>End of the second day</b>	

The EIPC is not responsible for the content and the presentation of the technical papers, which rests with the presenters. Changes in the programme may occur, due to circumstances, for which the EIPC may not be held responsible.

### **“STOCKHOLM EVENING TOUR BY BUS” AND “NETWORKING DINNER”**

At the end of the first Conference day we will all go to dinner on Thursday evening June 9 and then go on the “Stockholm evening Tour by Bus”. The guided bus tour, will show you some of Stockholm’s most interested sites and will drop us at the restaurant. The sightseeing tour and dinner is open to conference delegates and their guests. Why not participate and make this an unforgettable event for you and your customers. For delegates this tour and dinner is included in the conference fee. If you would like to order additional tickets for your guests, you can indicate this on the conference registration form or you can order tickets by sending an e-mail to [kwestenberg@eipc.org](mailto:kwestenberg@eipc.org).

### **TABLE-TOP EXHIBITION AND POSTER DISPLAY AREA**

During the EIPC Summer Conference Stockholm the EIPC will provide an opportunity for information sharing and discussion in a dedicated area. This will allow visitors to obtain latest product information and know how on an informal, or ‘one-to-one’ basis. A ‘Poster Wall’ and a table will be provided during the two days of the conference.

Kindly note that space for the Table Top Exhibition is limited, so you are asked to book as early as possible. Please note: costs for the ‘Table Top and Poster Display’ includes one person for coffee breaks and lunch. Conference participation fee is not included. If you are interested please submit the enclosed form from page 8.

### **DETAILED INFORMATION ABOUT THE CONFERENCE HOTEL**

The conference will be held on Thursday June 9 and Friday June 10, 2005 at the Scandic Infra City Hotel Upplands Väsby, Stockholm ([www.scandic-hotels.com](http://www.scandic-hotels.com)).

The Scandic Infra City hotel is Scandinavia’s largest Conference- Congress and Exhibition hotel on the north of Stockholm in between Arlanda International Airport and Stockholm City Centre. You are greeted by a light, open atmosphere and modern meeting facilities with the latest technology. The Scandic Infra City Hotel has 320 spacious rooms, many of them in bright Nordic design. Some of the rooms include a kitchenette for those who wish to stay longer or are traveling with the family. The lobby is a natural meeting place with a tropic garden, bar and lounge. The hotel is close to the business region, golf courses and nature as well as the cultural and entertainment venues of the city centre.

Rooms including non-smoking, standard and superior rooms, allergy-free rooms, some rooms with disabled facilities, and suites. All rooms have shower/bath, cable TV, telephone, writing desk, hair dryer, trouser press and air-conditioning. Superior rooms and suites additionally with minibar, coffee/tea maker iron/ironing board, some also with kitchenette. Many rooms have a bed closet with an extra bed. Wireless internet in the lobby and public areas.

Enjoy a delicious meal in restaurant Flavours. The kitchen offers inventive menus inspired by tastes from all over the world. All dishes are made from fresh ingredients of the season. You are seated in the tropical garden with palm trees and a pond. Here, at the heart of the hotel, is also the Atrium Bar and Lounge. You can lean back in an easy chair, order a good drink, a light snack. Breakfast is served in The Ocean Room.

### **SPONSORING THE EIPC SUMMER CONFERENCE STOCKHOLM**

The EIPC offers several possibilities for sponsoring the EIPC Summer Conference Stockholm 2005. Please find the various possibilities that could be a great asset to your company’s exposure on the following page.

**TO SAFE MONEY MAKE SURE YOU PAY BEFORE THE CONFERENCE STARTS. ON SITE HANDLING CHARGES ARE 30 EURO EXTRA.**

## **Sponsoring the EIPC Summer Conference Stockholm 2005**

### **A. Gold: 2,500 euro (max. 3 sponsors)**

One full colour advertisement in proceedings:

1. on back cover **or**;
2. next to programme Day One **or**;
3. next to programme Day Two.

One banner in conference room (banner being delivered by sponsor)

Logo/name on front page hard copy proceedings

Logo/name on the CD-Rom proceedings

Logo/name in official sponsor list

Logo/name will be listed in all outgoing communication

FREE Table Top + Poster Presentation (material being delivered by sponsor)

### **B. Silver: 1,800 euro (max. 3 sponsors)**

One full colour advertisement in the proceedings.

One banner in the conference room along the aisles (banner being delivered by sponsor)

Logo/name on front page hard copy proceedings

Logo/name on the CD-Rom proceedings

Logo/name in official sponsor list

Logo/name will be listed in all outgoing communication

FREE Table Top + Poster Presentation (being delivered by sponsor)

### **C. Bronze: 800 euro**

Logo/name on front page hard copy proceedings

Logo/name on the CD-Rom proceedings

Logo/name in official sponsor list

Logo/name will be listed in all outgoing communication

FREE Table Top + Poster Presentation (being delivered by sponsor)

### **D. Block notes Deal: 1000 euro**

Logo/name on front page hard copy proceedings

Logo/name on the CD-Rom proceedings

Logo/name in official sponsor list

Logo/name will be listed in all outgoing communication

Block notes and pens delivered by the sponsor for all delegates in conference bags or on the conference tables.

### **E. Conference bags Deal: 1000 euro**

Logo/name on front page hard copy proceedings

Logo/name on the CD-Rom proceedings

Logo/name in official sponsor list

Logo/name will be listed in all outgoing communication

Conference bags delivered by the sponsor for all delegates.

All other suggestions for sponsoring the EIPC Summer Conference are welcome, in consultation with the EIPC.

Kindly note that conference participation fee is not included.

## Submission Form for Sponsoring

**0 Yes, my company will be sponsoring the EIPC Summer Conference Stockholm  
We choose the following option:**

No.	Item	Price in EURO
0 A1	Gold	2500.-
0 A2	Gold	2500.-
0 A3	Gold	2500.-
0 B	Silver	1800.-
0 C	Bronze	800.-
0 D	Notepads and pens in Conference room	1000.-
0 E	Conference bags delivered by sponsor	1000.-

<b>Name:</b>	<b>First Name:</b>
<b>Company name:</b>	<b>Job title:</b>
<b>Address:</b>	<b>Postal code:</b>
<b>City:</b>	<b>Country:</b>
<b>Phone:</b>	<b>Fax:</b>
<b>E-mail:</b>	<b>Website:</b>
<b>Date:</b>	<b>Signature:</b>

Fax to: Kirsten Smit-Westenberg, Event Manager, EIPC, Maastricht, the Netherlands,  
Tel: +31 43 3440872, e-mail: [kwestenberg@eipc.org](mailto:kwestenberg@eipc.org)

**Please send your fax order to EIPC No.: +31 43 3440873**

**Conference Registration Form**  
**EIPC Summer Conference Stockholm, June 9 & 10, 2005**

Name:		First name:			
Company name:		Job title:			
Address:		Postal code:			
City:		Country:			
Telephone:		Fax:			
E-mail:		EIPC Membership no.:			
Date:		Signature:			
<input type="checkbox"/> Payment by credit card	Holder of card .....	<input type="checkbox"/> Master Card <input type="checkbox"/> VISA	Credit card number: .....	Expiry date: .....	
<input type="checkbox"/> Bank transfer after invoice					
<input type="checkbox"/> On site payment					
EURO 30.- Extra (administration costs)					
	Prices in Euro Before <b>May 2</b>		Prices in Euro After <b>May 2</b>		
	<b>Members</b>	Non-members	<b>Members</b>	Non-members	Amount €
<b>Full Conference</b> 2 days lecture, proceedings, coffee breaks, lunches and evening tour/dinner <b>I will take part in the evening program</b> <input type="checkbox"/> Yes <input type="checkbox"/> No	575.-	710.-	655.-	790.-	
<b>One day conference</b> 1 day lecture, proceedings, coffee breaks, lunches and evening tour/dinner <b>Please indicate the day:</b> <input type="checkbox"/> Thursday June 9 <input type="checkbox"/> Friday June 10 <b>I will take part in the evening program</b> <input type="checkbox"/> Yes <input type="checkbox"/> No	385.-	460.-	435.-	510.-	
<b>Speakers only</b> 2 days lecture, proceedings, coffee breaks, lunches and evening tour/dinner <b>I will take part in the evening program</b> <input type="checkbox"/> Yes <input type="checkbox"/> No	225.-	225.-			
<b>Groups Full Conference</b> 5 delegates from one company <b>We will take part in the evening program</b> <input type="checkbox"/> Yes <input type="checkbox"/> No	2675.-	3350.-	3075.-	3750.-	
<b>Extra Evening Tour/Dinner June 9</b> Please indicate the number of <b>EXTRA</b> tickets:	80.-	90.-			
<b>Post Conference Tour incl. lunch</b>	120.-	135.-			
				<b>Total in €</b>	

**Cancellation Policy: Cancellation before May 12, 2005: 50% refund/Cancellation after May 12, 2005: No refund.**

For more information, please contact K. Smit-Westenberg at 0031-43-3440872 or [kwestenberg@eipc.org](mailto:kwestenberg@eipc.org)

Please fax back to EIPC fax no. 0031-43-3440873

## Submission Form for Table Top & Poster Display

Limited space available!

### Table Top Exhibition and Poster Display Area

During The EIPC Summer Conference the EIPC will provide an opportunity for information sharing and discussion in dedicated areas. This will allow for visitors to obtain latest product information and know-how on an informal, or 'one-to-one' basis.

A poster wall and a table will be provided during the two days of the event.

Costs	Before May 2 <sup>nd</sup>	After May 2 <sup>nd</sup>
Members	0 euro 375.-	0 euro 425.-
Non member	0 euro 500.-	0 euro 575.-

*(Please indicate your choice)*

Kindly note that space for the Table Top Exhibition is limited, so you are asked to book as early as possible. Conference participation fee is NOT included.

Payment method: bank transfer after receipt of invoice.

**Benefit from the reduced rate and book your Table Top & Poster Display before May 2<sup>nd</sup>, 2005!**

Yes, I will book a Table Top & Poster display at the EIPC Summer Conference Stockholm

Name:	First Name:
Company name:	Job title:
Address:	Postal code:
City:	Country:
Phone:	Fax:
E-mail:	Website:
Date:	Signature:

Fax to: Kirsten Smit-Westenberg, Event Manager, EIPC, Maastricht, the Netherlands,  
Tel: +31 43 3440872, e-mail: [kwestenberg@eipc.org](mailto:kwestenberg@eipc.org)

**Please send your fax order to EIPC No.: +31 43 3440873**



**HOTEL RESERVATION FORM**

**EIPC Summer Conference, Stockholm 9-10<sup>th</sup> of June 2005**

Room	8/6	Price	9/6	Price	10/6	Price	11/6	Price	12/6	Price
Single standard		1350:-		1350:-		1350:-		1350:-		1350:-
Double standard		1550:-		1550:-		1550:-		1550:-		1550:-

*The Roomrate includes VAT & Breakfast*

Name	Date	Remarks

**Confirmation Number:** \_\_\_\_\_ (will be sent back by hotel)

**Please fill in the below details to make a reservation. PLEASE write in block letters.**

<b>Company</b>			
<b>Contact Person</b>			
<b>Address</b>			
<b>Postal code /City</b>			
<b>Telephonenumber</b>		<b>Fax</b>	
<b>e-mail</b>			

**Please fill in payment details:**

<b>Creditcard</b>		<b>For approval please fill in all details</b>
<b>Cash</b>		

**Payment by creditcard, we need following details:**

<b>Owner of Creditcard</b>	<b>AX/EU/MC/Visa</b>	<b>Creditcard number</b>	<b>Expiry date</b>
			/

Above rates are stated in Swedish Krona, SEK.

**PLEASE NOTE: If above details is not filled in correctly the room will not be guaranteed for late arrival. And will give us the right to sell the room after 6pm the day of arrival**

Cancellationpolicy: 6pm the day of arrival.

Send this reservationform by fax to Scandic Infra City. Faxnumber **+468 517 344 75**

A confirmation with confirmation number and rates will be sent back by the hotel.

The reservation is confirmed when Scandic Infra City have signed this form.

**Above Details approved**  
2005- /

**Signature from Scandic Infra City**  
2005- /

**Address: Kanalvägen 10**  
**S-19461 Upplands Väsby**  
**Sweden**  
**Telephonenumber: +468 517 344 00**